

## Amendments to the Claims

and

### Listing of Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

Claim 14 is amended.

1-13. (canceled)

14. (currently amended) A method for manufacturing an electronic device comprising:

placing within a die a first lead with an element placement pad having a thickness  $t$  of less than 0.1 mm, a second lead that is disposed at a distance from said element placement pad, and an electronic element placed on said element placement pad; and

sealing in a package said electronic element, said element placement pad, a part of said first lead, and a part of said second lead by injecting a sealing resin, in a direction substantially parallel to a surface of said element placement pad, in the die from a position on a longer side of the package, said position being offset toward one shorter side thereof.

wherein said first lead is bent in an S shape so as to extend within the package towards a side of the package that is opposite from a side where the electronic element is placed with respect to the element placement pad, a bending depth  $d$  therefore being at least as large as the thickness  $t$  of said first lead, and a thickness  $T$  of said resin on a non-device side of said element placement pad is smaller than said bending depth  $d$ .

15. (previously presented) The method according to claim 14, wherein the spacing between said element placement pad and said second lead is no greater than 0.12 mm.

16. (previously presented) The method according to claim 14, wherein the vertical, horizontal and height outer dimensions of said sealing resin are each no greater than 1.0 mm.
17. (previously presented) The method according to claim 14, wherein widths of inner lead parts of said first and second leads within said sealing resin are substantially uniform.
18. (previously presented) The method according to claim 14, wherein the thickness of said electronic element is substantially the same as the thickness  $t$  of said first lead.
19. (previously presented) The method according to claim 14, wherein a bending radius  $R$  on an outer surface of a bent part of said first lead near a bottom surface of said sealing resin is at least 0.05 mm and is no greater than the lead thickness  $t$ .
20. (previously presented) The method according to claim 14, wherein the sealing resin contains a filler, whose particle diameter is not greater than half the bending depth  $d$  of the said first lead.